[NAME OF DOCUMENT] ABSTRACT OF THE DISCLOSURE

[ABSTEACT]

[Subject]

The object of the present invention is provide a semiconductor device in semiconductor package configuration, characterized by excellent connection reliability ensured by incorporating a buffer for absorbing differences in thermal expansion rate between a mounting substrate and a semiconductor element even when an organic material is used for a mounting substrate.

[Solving Means]

A semiconductor device characterized by using a film material as a buffer for thermal stress resulting from differences in thermal expansion rate between a semiconductor element and a mounting substrate. This device is also characterized in that the modulus of elasticity of the aforementioned film material in the reflow temperature range (200 to 250 degrees Celsius) does not exceed 1 MPa.

[Selected Figure] FIG. 2